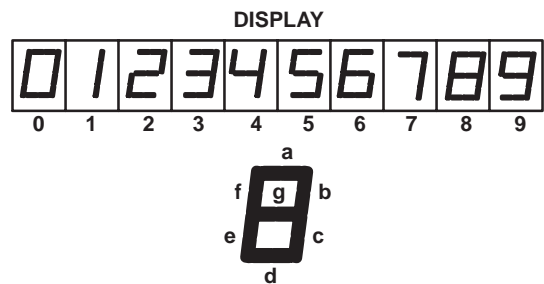
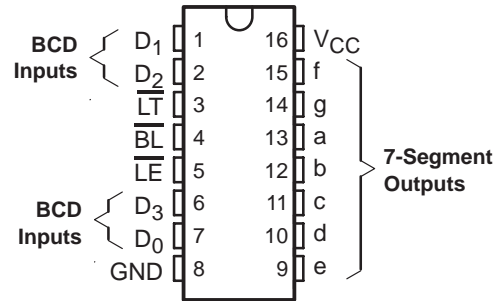


CD54HC4511, CD74HC4511, CD74HCT4511 BCD-TO-7 SEGMENT LATCH/DECODER/DRIVERS

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- 2-V to 6-V V_{CC} Operation ('HC4511)
- 4.5-V to 5.5-V V_{CC} Operation (CD74HCT4511)
- High-Output Sourcing Capability
 - 7.5 mA at 4.5 V (CD74HCT4511)
 - 10 mA at 6 V ('HC4511)
- Input Latches for BCD Code Storage
- Lamp Test and Blanking Capability
- Balanced Propagation Delays and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- 'HC4511
 - High Noise Immunity, N_{IL} or $N_{IH} = 30\%$ of V_{CC} at $V_{CC} = 5$ V
- CD74HCT4511
 - Direct LSTTL Input Logic Compatibility, $V_{IL} = 0.8$ V Maximum, $V_{IH} = 2$ V Minimum
 - CMOS Input Compatibility, $I_1 \leq 1$ μ A at V_{OL} , V_{OH}

CD54HC4511 ... F PACKAGE
CD74HC4511 ... E, M, OR PW PACKAGE
CD74HCT4511 ... E PACKAGE
(TOP VIEW)



description/ordering information

The CD54HC4511, CD74HC4511, and CD74HCT4511 are BCD-to-7 segment latch/decoder/drivers with four address inputs (D_0 – D_3), an active-low blanking (\overline{BL}) input, lamp-test (\overline{LT}) input, and a latch-enable (\overline{LE}) input that, when high, enables the latches to store the BCD inputs. When \overline{LE} is low, the latches are disabled, making the outputs transparent to the BCD inputs.

These devices have standard-size output transistors, but are capable of sourcing (at standard V_{OH} levels) up to 7.5 mA at 4.5 V. The HC types can supply up to 10 mA at 6 V.

ORDERING INFORMATION

| T_A | PACKAGE† | | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|----------------|------------|---|-----------------------|------------------|
| –55°C to 125°C | PDIP – E | Tube of 25 | CD74HC4511E | CD74HC4511E |
| | | | CD74HCT4511E | CD74HCT4511E |
| | SOIC – M | Tube of 40 Reel of 2500 Reel of 250 | CD74HC4511M | HC4511M |
| | | | CD74HC4511M96 | |
| | | | CD74HC4511MT | |
| | TSSOP – PW | Reel of 2000 Reel of 250 | CD74HC4511PWR | HJ4511 |
| | | | CD74HC4511PWT | |
| CDIP – F | Tube of 25 | CD54HC4511F3A | CD54HC4511F3A | |

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

CD54HC4511, CD74HC4511, CD74HCT4511 BCD-TO-7 SEGMENT LATCH/DECODER/DRIVERS

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FUNCTION TABLE

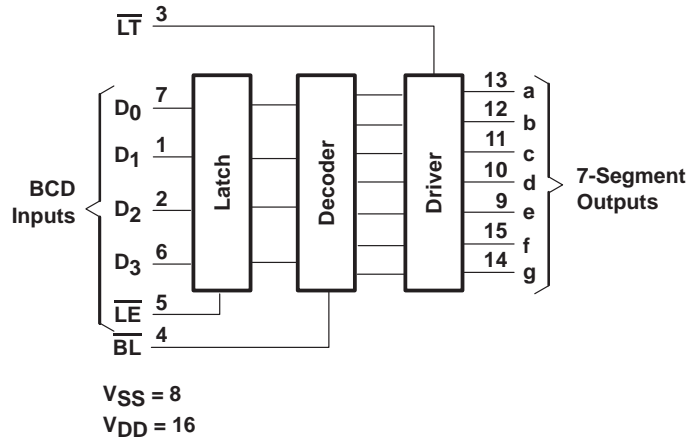
| INPUTS | | | | | | | | OUTPUTS | | | | | | | |
|-----------------|-----------------|-----------------|----------------|----------------|----------------|----------------|--|---------|---|---|---|---|---|---|---------|
| \overline{LE} | \overline{BL} | \overline{LT} | D ₃ | D ₂ | D ₁ | D ₀ | | a | b | c | d | e | f | g | DISPLAY |
| X | X | L | X | X | X | X | | H | H | H | H | H | H | H | 8 |
| X | L | H | X | X | X | X | | L | L | L | L | L | L | L | Blank |
| L | H | H | L | L | L | L | | H | H | H | H | H | H | L | 0 |
| L | H | H | L | L | L | H | | L | H | H | L | L | L | L | 1 |
| L | H | H | L | L | H | L | | H | H | L | H | H | L | H | 2 |
| L | H | H | L | L | H | H | | H | H | H | H | L | L | H | 3 |
| L | H | H | L | H | L | L | | L | H | H | L | L | H | H | 4 |
| L | H | H | L | H | L | H | | H | L | H | H | L | H | H | 5 |
| L | H | H | L | H | H | L | | L | L | H | H | H | H | H | 6 |
| L | H | H | L | H | H | H | | H | H | H | L | L | L | L | 7 |
| L | H | H | H | L | L | L | | H | H | H | H | H | H | H | 8 |
| L | H | H | H | L | L | H | | H | H | H | L | L | H | H | 9 |
| L | H | H | H | L | H | L | | L | L | L | L | L | L | L | Blank |
| L | H | H | H | L | H | H | | L | L | L | L | L | L | L | Blank |
| L | H | H | H | H | L | L | | L | L | L | L | L | L | L | Blank |
| L | H | H | H | H | L | H | | L | L | L | L | L | L | L | Blank |
| L | H | H | H | H | H | L | | L | L | L | L | L | L | L | Blank |
| L | H | H | H | H | H | H | | L | L | L | L | L | L | L | Blank |
| H | H | H | X | X | X | X | | † | † | † | † | † | † | † | † |

X = Don't care

† Depends on BCD code previously applied when $\overline{LE} = L$

NOTE: Display is blank for all illegal input codes (BCD > HLLH).

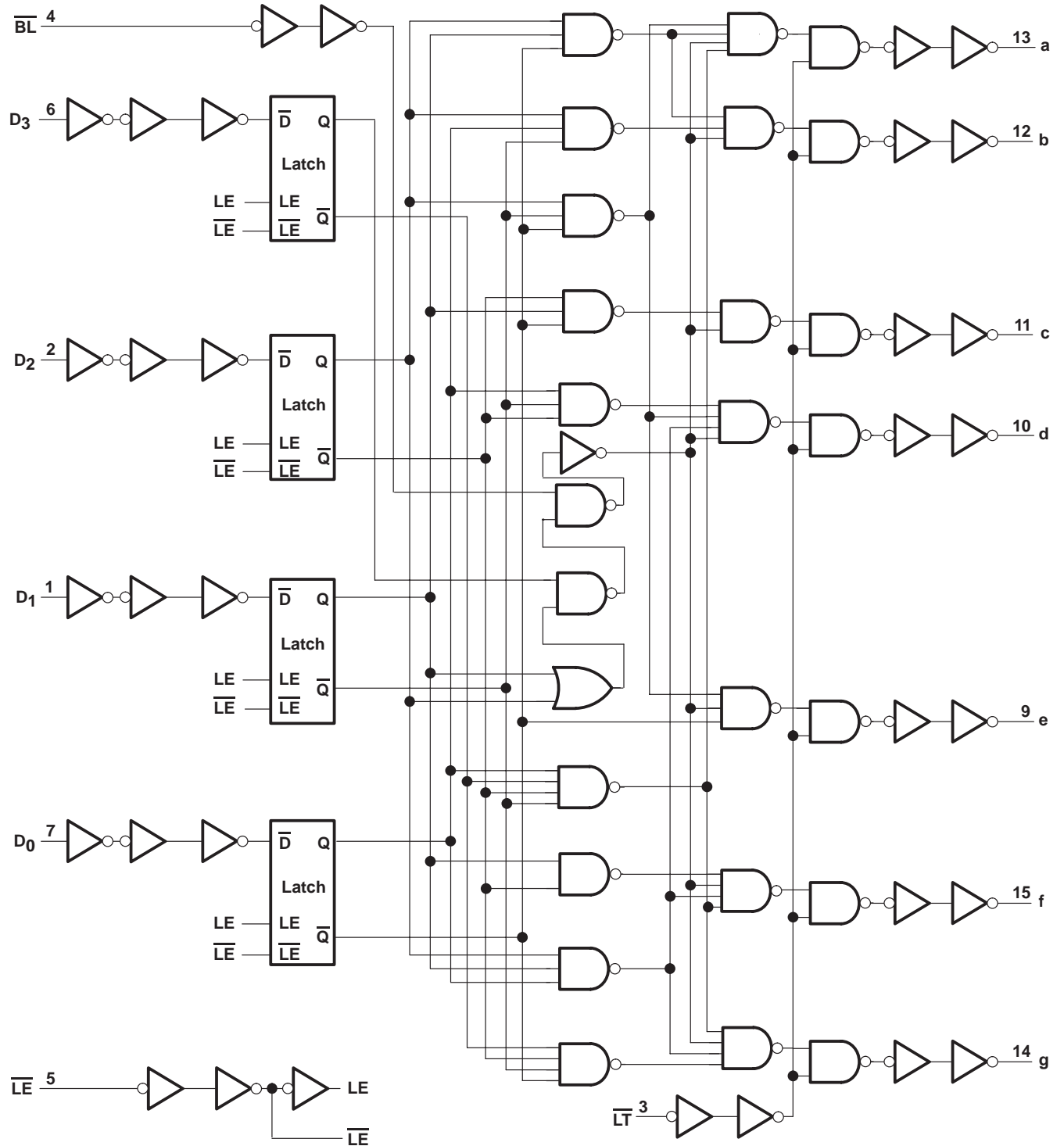
function diagram



CD54HC4511, CD74HC4511, CD74HCT4511 BCD-TO-7 SEGMENT LATCH/DECODER/DRIVERS

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logic diagram



CD54HC4511, CD74HC4511, CD74HCT4511 BCD-TO-7 SEGMENT LATCH/DECODER/DRIVERS

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absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

| | |
|--|---------------|
| Supply voltage range, V_{CC} | -0.5 V to 7 V |
| Input diode current, I_{IK} ($V_I < -0.5$ V or $V_I > V_{CC} + 0.5$ V) (see Note 1) | ± 20 mA |
| Output diode current, I_{OK} ($V_O < -0.5$ V or $V_O > V_{CC} + 0.5$ V) (see Note 1) | ± 20 mA |
| Continuous output source or sink current per output, I_O ($V_O = 0$ to V_{CC}) | ± 25 mA |
| Continuous current through V_{CC} or GND | ± 50 mA |
| Package thermal impedance, θ_{JA} (see Note 2): E package | 67°C/W |
| M package | 73°C/W |
| PW package | 108°C/W |
| Lead temperature (during soldering): | |
| At distance $1/16 \pm 1/32$ in (1.59 ± 0.79 mm) from case for 10 s maximum | 265°C |
| Unit inserted into a PC board (minimum thickness $1/16$ in, 1.59 mm), with solder contacting lead tips only | 300°C |
| Storage temperature, T_{stg} | -65 to 150°C |

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions for 'HC4511 (see Note 3)

| | | $T_A = 25^\circ\text{C}$ | | $T_A = -55^\circ\text{C}$ TO 125°C | | $T_A = -40^\circ\text{C}$ TO 85°C | | UNIT |
|----------|---------------------------------------|--------------------------|----------|---|----------|--|----------|------|
| | | MIN | MAX | MIN | MAX | MIN | MAX | |
| V_{CC} | Supply voltage | 2 | 6 | 2 | 6 | 2 | 6 | V |
| V_{IH} | High-level input voltage | $V_{CC} = 2$ V | 1.5 | 1.5 | 1.5 | 1.5 | | V |
| | | $V_{CC} = 4.5$ V | 3.15 | 3.15 | 3.15 | | | |
| | | $V_{CC} = 6$ V | 4.2 | 4.2 | 4.2 | | | |
| V_{IL} | Low-level input voltage | $V_{CC} = 2$ V | 0.5 | 0.5 | 0.5 | | V | |
| | | $V_{CC} = 4.5$ V | 1.35 | 1.35 | 1.35 | | | |
| | | $V_{CC} = 6$ V | 1.8 | 1.8 | 1.8 | | | |
| V_I | Input voltage | 0 | V_{CC} | 0 | V_{CC} | 0 | V_{CC} | V |
| V_O | Output voltage | 0 | V_{CC} | 0 | V_{CC} | 0 | V_{CC} | V |
| t_t | Input transition (rise and fall) time | $V_{CC} = 2$ V | 1000 | 1000 | 1000 | | ns | |
| | | $V_{CC} = 4.5$ V | 500 | 500 | 500 | | | |
| | | $V_{CC} = 6$ V | 400 | 400 | 400 | | | |

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



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recommended operating conditions for CD74HCT4511 (see Note 4)

| | | T _A = 25°C | | T _A = -55°C TO 125°C | | T _A = -40°C TO 85°C | | UNIT |
|-----------------|---------------------------------------|-----------------------|-----------------|---------------------------------|-----------------|--------------------------------|-----------------|------|
| | | MIN | MAX | MIN | MAX | MIN | MAX | |
| V _{CC} | Supply voltage | 4.5 | 5.5 | 4.5 | 5.5 | 4.5 | 5.5 | V |
| V _{IH} | High-level input voltage | 2 | | 2 | | 2 | | V |
| V _{IL} | Low-level input voltage | | 0.8 | | 0.8 | | 0.8 | V |
| V _I | Input voltage | | V _{CC} | | V _{CC} | | V _{CC} | V |
| V _O | Output voltage | | V _{CC} | | V _{CC} | | V _{CC} | V |
| t _t | Input transition (rise and fall) time | | 500 | | 500 | | 500 | ns |

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

'HC4511

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | V _{CC} | T _A = 25°C | | T _A = -55°C TO 125°C | | T _A = -40°C TO 85°C | | UNIT |
|-----------------|---|---------------------------|-----------------------|------|---------------------------------|------|--------------------------------|-----|------|
| | | | MIN | MAX | MIN | MAX | MIN | MAX | |
| V _{OH} | V _I = V _{IH} or V _{IL} | I _{OH} = -20 μA | 2 V | 1.9 | 1.9 | 1.9 | | V | |
| | | | 4.5 V | 4.4 | 4.4 | 4.4 | | | |
| | | | 6 V | 5.9 | 5.9 | 5.9 | | | |
| | | I _{OH} = -7.5 mA | 4.5 V | 3.98 | 3.7 | 3.84 | | | |
| | | I _{OH} = -10 mA | 6 V | 5.48 | 5.2 | 5.34 | | | |
| V _{OL} | V _I = V _{IH} or V _{IL} | I _{OL} = 20 μA | 2 V | 0.1 | 0.1 | 0.1 | V | | |
| | | | 4.5 V | 0.1 | 0.1 | 0.1 | | | |
| | | | 6 V | 0.1 | 0.1 | 0.1 | | | |
| | | I _{OL} = 4 mA | 4.5 V | 0.26 | 0.4 | 0.33 | | | |
| | | I _{OL} = 5.2 mA | 6 V | 0.26 | 0.4 | 0.33 | | | |
| I _I | V _I = V _{CC} or 0 | 6 V | | ±0.1 | ±1 | ±1 | μA | | |
| I _{CC} | V _I = V _{CC} or 0, I _O = 0 | 6 V | | 8 | 160 | 80 | μA | | |
| C _i | | | | 10 | 10 | 10 | pF | | |

CD54HC4511, CD74HC4511, CD74HCT4511 BCD-TO-7 SEGMENT LATCH/DECODER/DRIVERS

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CD74HCT4511

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | | V _{CC} | T _A = 25°C | | | T _A = -55°C TO 125°C | | T _A = -40°C TO 85°C | | UNIT |
|--------------------|--|--------------------------|-----------------|-----------------------|-----|-----|---------------------------------|-----|--------------------------------|-----|------|
| | | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| V _{OH} | V _I = V _{IH} or V _{IL} | I _{OH} = -20 μA | 4.5 V | 4.4 | | | 4.4 | | 4.4 | | V |
| | | I _{OH} = -4 mA | | 3.98 | | | 3.7 | | 3.84 | | |
| V _{OL} | V _I = V _{IH} or V _{IL} | I _{OL} = 20 μA | 4.5 V | 0.1 | | | 0.1 | | 0.1 | | V |
| | | I _{OL} = 4 mA | | 0.26 | | | 0.4 | | 0.33 | | |
| I _I | V _I = V _{CC} to GND | | 5.5 V | ±0.1 | | | ±1 | | ±1 | | μA |
| I _{CC} | V _I = V _{CC} or 0, I _O = 0 | | 5.5 V | 8 | | | 160 | | 80 | | μA |
| ΔI _{CC} † | One input at V _{CC} - 2.1 V, Other inputs at 0 or V _{CC} | | 4.5 V to 5.5 V | 100 360 | | | 490 | | 450 | | μA |
| C _i | | | | 10 | | | 10 | | 10 | | pF |

† Additional quiescent supply current per input pin, TTL inputs high, 1 unit load. For dual-supply systems, theoretical worst-case (V_I = 2.4 V, V_{CC} = 5.5 V) specification is 1.8 mA.

HCT INPUT LOADING TABLE

| INPUT | UNIT LOADS‡ |
|---|-------------|
| $\overline{L\bar{T}}$, $\overline{L\bar{E}}$ | 1.5 |
| $\overline{B\bar{L}}$, D _n | 0.3 |

‡ Unit load is ΔI_{CC} limit specified in electrical characteristics table, e.g., 360 μA maximum at 25°C.

HC4511 timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

| | V _{CC} | T _A = 25°C | | T _A = -55°C TO 125°C | | T _A = -40°C TO 85°C | | UNIT |
|---|-----------------|-----------------------|-----|---------------------------------|-----|--------------------------------|-----|------|
| | | MIN | MAX | MIN | MAX | MIN | MAX | |
| t _w Pulse duration, $\overline{L\bar{E}}$ low | 2 V | 80 | | 120 | | 100 | | ns |
| | 4.5 V | 16 | | 24 | | 20 | | |
| | 6 V | 14 | | 20 | | 17 | | |
| t _{su} Setup time, BCD inputs before $\overline{L\bar{E}}\uparrow$ | 2 V | 60 | | 90 | | 75 | | ns |
| | 4.5 V | 12 | | 18 | | 15 | | |
| | 6 V | 10 | | 15 | | 13 | | |
| t _h Hold time, BCD inputs before $\overline{L\bar{E}}\uparrow$ | 2 V | 3 | | 3 | | 3 | | ns |
| | 4.5 V | 3 | | 3 | | 3 | | |
| | 6 V | 3 | | 3 | | 3 | | |



CD54HC4511, CD74HC4511, CD74HCT4511 BCD-TO-7 SEGMENT LATCH/DECODER/DRIVERS

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'HC4511

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | LOAD CAPACITANCE | V _{CC} | T _A = 25°C | | | T _A = -55°C TO 125°C | | T _A = -40°C TO 85°C | | UNIT | |
|------------------------|------------------------|------------------------|------------------------|-----------------|-----------------------|-----|-----|---------------------------------|-----|--------------------------------|-----|------|----|
| | | | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | | |
| t _{pd} | D _n | Output | C _L = 50 pF | 2 V | | | 300 | | | 450 | | 375 | ns |
| | | | | 4.5 V | | | 60 | | | 90 | | 75 | |
| | | | 6 V | | | 51 | | | 77 | | 64 | | |
| | | | C _L = 15 pF | 5 V | | | 25 | | | | | | |
| | $\overline{\text{LE}}$ | Output | C _L = 50 pF | 2 V | | | 270 | | | 405 | | 340 | |
| | | | | 4.5 V | | | 54 | | | 81 | | 68 | |
| | | | 6 V | | | 46 | | | 69 | | 58 | | |
| | | | C _L = 15 pF | 5 V | | | 23 | | | | | | |
| | $\overline{\text{BL}}$ | Output | C _L = 50 pF | 2 V | | | 220 | | | 330 | | 275 | |
| | | | | 4.5 V | | | 44 | | | 66 | | 55 | |
| | | | 6 V | | | 37 | | | 56 | | 47 | | |
| | | | C _L = 15 pF | 5 V | | | 18 | | | | | | |
| $\overline{\text{LT}}$ | Output | C _L = 50 pF | 2 V | | | 160 | | | 240 | | 200 | | |
| | | | 4.5 V | | | 32 | | | 48 | | 40 | | |
| | | 6 V | | | 27 | | | 41 | | 34 | | | |
| | | C _L = 15 pF | 5 V | | | 13 | | | | | | | |
| t _t | | Any | C _L = 50 pF | 2 V | | | 75 | | | 110 | | 95 | ns |
| | | | | 4.5 V | | | 15 | | | 22 | | 19 | |
| | | | | 6 V | | | 13 | | | 19 | | 16 | |

CD54HC4511, CD74HC4511, CD74HCT4511 BCD-TO-7 SEGMENT LATCH/DECODER/DRIVERS

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CD74HCT4511

timing requirements over recommended operating free-air temperature range $V_{CC} = 4.5\text{ V}$ (unless otherwise noted) (see Figure 2)

| | | $T_A = 25^\circ\text{C}$ | | $T_A = -55^\circ\text{C}$ TO 125°C | | $T_A = -40^\circ\text{C}$ TO 85°C | | UNIT |
|----------|---|--------------------------|-----|---|-----|--|-----|------|
| | | MIN | MAX | MIN | MAX | MIN | MAX | |
| t_w | Pulse duration, \overline{LE} low | 16 | | 24 | | 20 | | ns |
| t_{su} | Setup time, BCD inputs before $\overline{LE}\uparrow$ | 16 | | 24 | | 20 | | ns |
| t_h | Hold time, BCD inputs before $\overline{LE}\uparrow$ | 5 | | 5 | | 5 | | ns |

CD74HCT4511

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 2)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | LOAD CAPACITANCE | V_{CC} | $T_A = 25^\circ\text{C}$ | | | $T_A = -55^\circ\text{C}$ TO 125°C | | $T_A = -40^\circ\text{C}$ TO 85°C | | UNIT | |
|-----------------|-----------------|----------------------|----------------------|----------|--------------------------|-----|-----|---|-----|--|-----|------|----|
| | | | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | | |
| t_{pd} | D_n | Output | $C_L = 50\text{ pF}$ | 4.5 V | | | 60 | | 90 | | 75 | ns | |
| | | | $C_L = 15\text{ pF}$ | 5 V | | | 25 | | | | | | |
| | \overline{LE} | Output | $C_L = 50\text{ pF}$ | 4.5 V | | | | | 54 | | 81 | | 68 |
| | | | $C_L = 15\text{ pF}$ | 5 V | | | 23 | | | | | | |
| | \overline{BL} | Output | $C_L = 50\text{ pF}$ | 4.5 V | | | | | | | 66 | | 55 |
| | | | $C_L = 15\text{ pF}$ | 5 V | | | 18 | | | | | | |
| \overline{LT} | Output | $C_L = 50\text{ pF}$ | 4.5 V | | | | | | | 50 | 41 | | |
| | | $C_L = 15\text{ pF}$ | 5 V | | | 13 | | | | | | | |
| t_t | | Any | $C_L = 50\text{ pF}$ | 4.5 V | | | | 15 | | 22 | 19 | ns | |

operating characteristics, $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

| PARAMETER | | TYP | UNIT |
|-----------------|-------------------------------|-------------|------|
| $C_{pd}\dagger$ | Power dissipation capacitance | 'HC4511 | 114 |
| | | CD74HCT4511 | 110 |

$\dagger C_{pd}$ is used to determine the dynamic power consumption, per package.

$$P_D = C_{pd} V_{CC}^2 f_i + \sum C_L V_{CC}^2 f_o$$

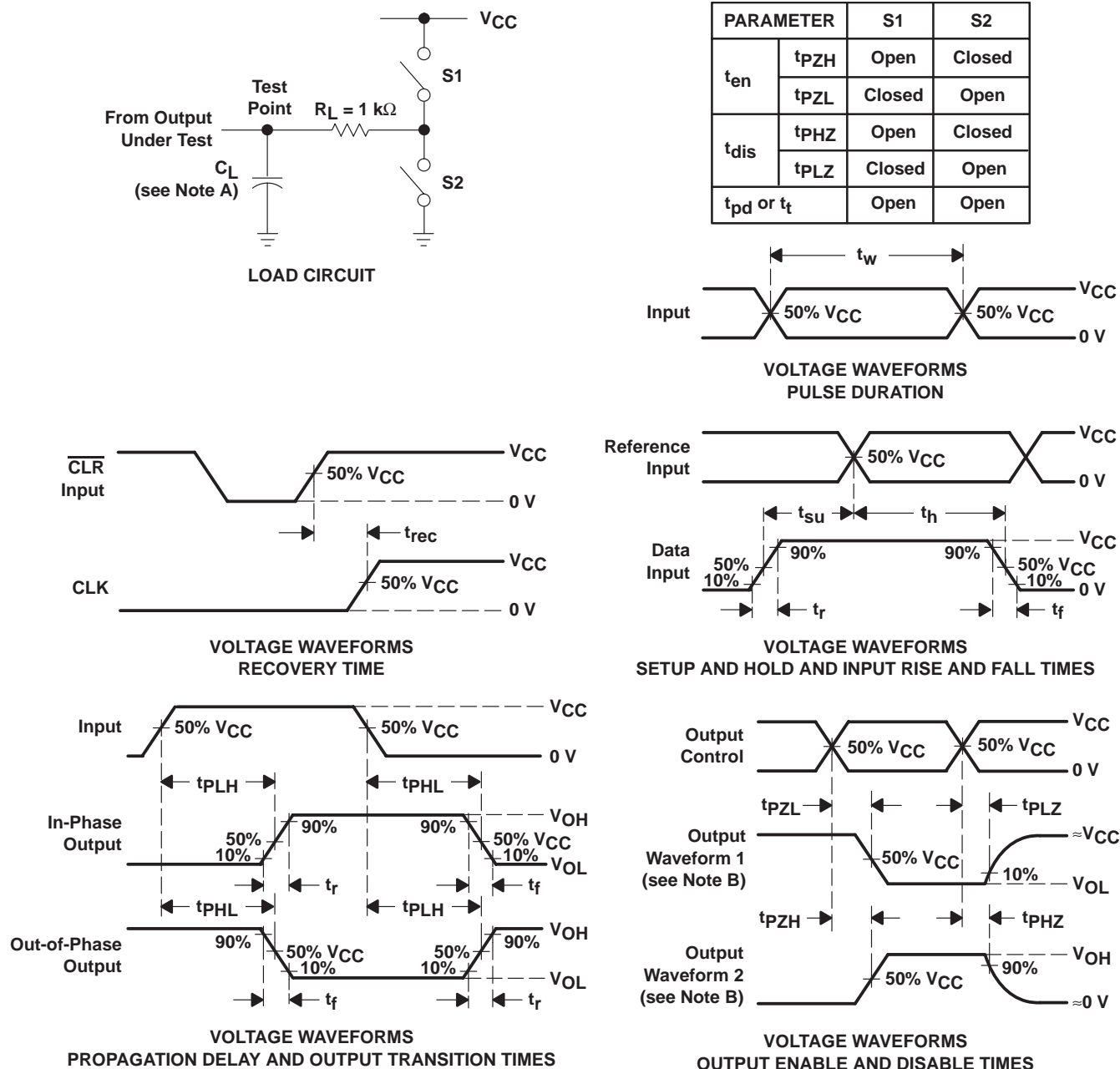
where: f_i = input frequency

f_o = output frequency

C_L = output load capacitance

V_{CC} = supply voltage

PARAMETER MEASUREMENT INFORMATION – 'HC4511



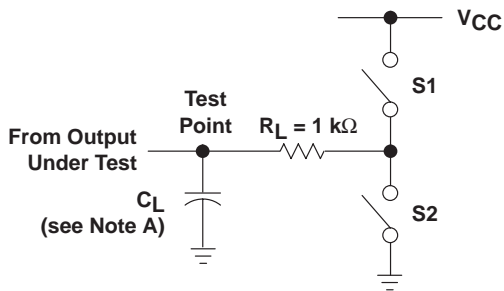
- NOTES:
- A. C_L includes probe and test-fixture capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r = 6\text{ ns}$, $t_f = 6\text{ ns}$.
 - D. For clock inputs, f_{max} is measured with the input duty cycle at 50%.
 - E. The outputs are measured one at a time with one input transition per measurement.
 - F. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - G. t_{PZL} and t_{PZH} are the same as t_{en} .
 - H. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

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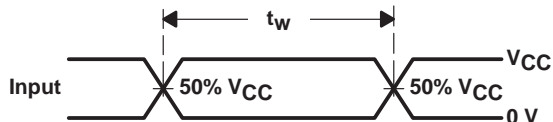
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PARAMETER MEASUREMENT INFORMATION – CD74HCT4511

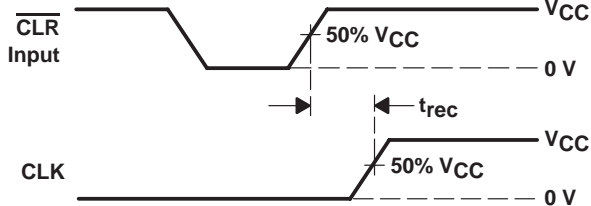


LOAD CIRCUIT

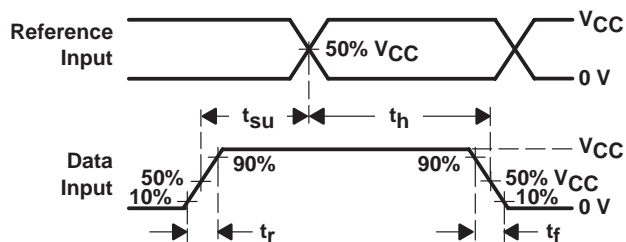
| PARAMETER | S1 | S2 | |
|-------------------|-----------|--------|--------|
| t_{en} | t_{PZH} | Open | Closed |
| | t_{PZL} | Closed | Open |
| t_{dis} | t_{PHZ} | Open | Closed |
| | t_{PLZ} | Closed | Open |
| t_{pd} or t_t | Open | Open | |



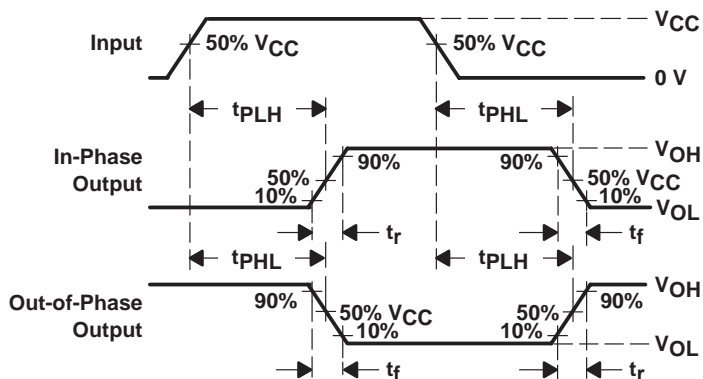
VOLTAGE WAVEFORMS
PULSE DURATION



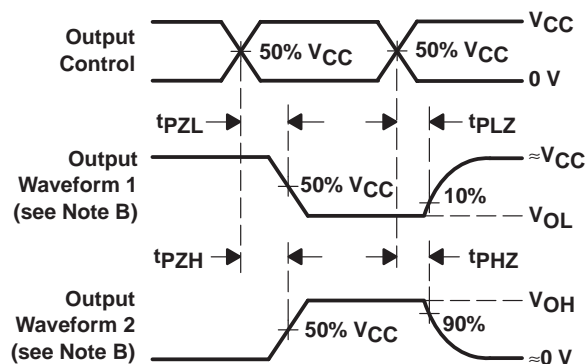
VOLTAGE WAVEFORMS
RECOVERY TIME



VOLTAGE WAVEFORMS
SETUP AND HOLD AND INPUT RISE AND FALL TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES



VOLTAGE WAVEFORMS
OUTPUT ENABLE AND DISABLE TIMES

- NOTES: A. C_L includes probe and test-fixture capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1$ MHz, $Z_O = 50 \Omega$, $t_r = 6$ ns, $t_f = 6$ ns.
 D. For clock inputs, f_{max} is measured with the input duty cycle at 50%.
 E. The outputs are measured one at a time with one input transition per measurement.
 F. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 G. t_{PZL} and t_{PZH} are the same as t_{en} .
 H. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 2. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|--------------------|------|----------------|----------------------------|------------------|----------------------|--------------|---------------------------------|-------------------------|
| 5962-8773301EA | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 5962-8773301EA CD54HC4511F3A | Samples |
| CD54HC4511F3A | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 5962-8773301EA CD54HC4511F3A | Samples |
| CD74HC4511E | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | -55 to 125 | CD74HC4511E | Samples |
| CD74HC4511EE4 | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | -55 to 125 | CD74HC4511E | Samples |
| CD74HC4511M | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HC4511M | Samples |
| CD74HC4511M96 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HC4511M | Samples |
| CD74HC4511M96E4 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HC4511M | Samples |
| CD74HC4511M96G4 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HC4511M | Samples |
| CD74HC4511ME4 | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HC4511M | Samples |
| CD74HC4511MG4 | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HC4511M | Samples |
| CD74HC4511MT | ACTIVE | SOIC | D | 16 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HC4511M | Samples |
| CD74HC4511MTE4 | ACTIVE | SOIC | D | 16 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HC4511M | Samples |
| CD74HC4511MTG4 | ACTIVE | SOIC | D | 16 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HC4511M | Samples |
| CD74HC4511PWR | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HJ4511 | Samples |
| CD74HC4511PWRE4 | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HJ4511 | Samples |
| CD74HC4511PWRG4 | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HJ4511 | Samples |
| CD74HC4511PWT | ACTIVE | TSSOP | PW | 16 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HJ4511 | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|--------------------|------|----------------|----------------------------|------------------|----------------------|--------------|-------------------------|-------------------------|
| CD74HC4511PWTE4 | ACTIVE | TSSOP | PW | 16 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HJ4511 | Samples |
| CD74HC4511PWTE4 | ACTIVE | TSSOP | PW | 16 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HJ4511 | Samples |
| CD74HCT4511E | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | -55 to 125 | CD74HCT4511E | Samples |
| CD74HCT4511EE4 | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | -55 to 125 | CD74HCT4511E | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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OTHER QUALIFIED VERSIONS OF CD54HC4511, CD74HC4511 :

- Catalog: [CD74HC4511](#)
- Military: [CD54HC4511](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


| | |
|----|---|
| A0 | Dimension designed to accommodate the component width |
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

TAPE AND REEL INFORMATION

*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| CD74HC4511M96 | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.1 | 8.0 | 16.0 | Q1 |
| CD74HC4511PWR | TSSOP | PW | 16 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |
| CD74HC4511PWT | TSSOP | PW | 16 | 250 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---------------|--------------|-----------------|------|------|-------------|------------|-------------|
| CD74HC4511M96 | SOIC | D | 16 | 2500 | 333.2 | 345.9 | 28.6 |
| CD74HC4511PWR | TSSOP | PW | 16 | 2000 | 367.0 | 367.0 | 35.0 |
| CD74HC4511PWT | TSSOP | PW | 16 | 250 | 367.0 | 367.0 | 35.0 |

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



| DIM \ PINS ** | 14 | 16 | 18 | 20 |
|---------------|------------------------|------------------------|------------------------|------------------------|
| A | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC |
| B MAX | 0.785 (19,94) | .840 (21,34) | 0.960 (24,38) | 1.060 (26,92) |
| B MIN | — | — | — | — |
| C MAX | 0.300 (7,62) | 0.300 (7,62) | 0.310 (7,87) | 0.300 (7,62) |
| C MIN | 0.245 (6,22) | 0.245 (6,22) | 0.220 (5,59) | 0.245 (6,22) |



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - $\triangle D$ The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

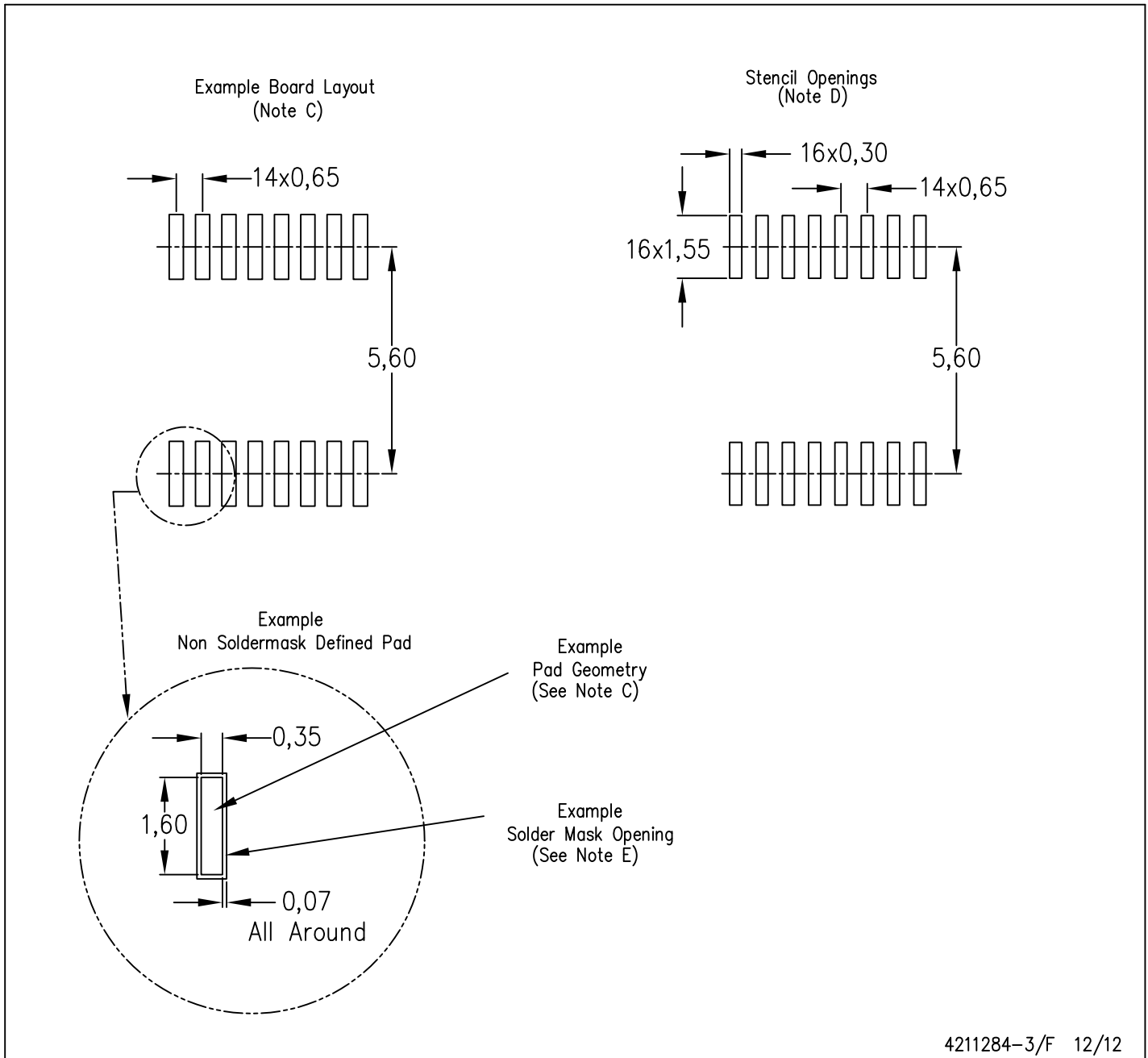
PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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